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Si Technology Leader

Advanced Process & Module Development (DRAM, Flash, Logic, etc.)

- Photolithography (e-beam, EUV, OPC/RET, Photo Resist Materials), Dry Etch, Cleaning & CMP, Diffusion, Ion Implantation, Metallization, Metrology & Inspection, etc.
- Device Isolation, Transistor, Capacitor, Dielectric
- High-K/Metal Gate, SD2/SDN Gate Dielectric
- Low-K, Interconnect, etc.

OPC : Optical Proximity Correction (Comput. Litho), MPC : Mask Process Correction
FEOL/BEOL Process Integration (DRAM / Flash / Logic, etc.)

TCAD/ECAD

- Process & Device/Material Modeling, Circuit Compact/Reliability Modeling
- Circuit Simulator Development
- System-Level Modeling / Simulation, Virtual Platform, HW / SW Co-Design
- Sincs/CoWare/SOC Designer Use Memory Controller/Memory Architecture/SSD Research Experience

Package Development

- Wire Bonding & Flip Chip Package / Wafer Level Package (WLP/TSV)
- Thinning PKG/Chip Waferpage Control, Signal/Power/Thermal
- Material Development & Failure Analysis

Material Development & Environment Contamination Control

- Material(Wafer, PR, Gas, Chemical, Thin Film) Development
- FAB Environment Contamination Monitoring & Control
- Material & Environment Failure Analysis and Quality Guarantee

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